

REMARKS

Claims 1, 3, 4 and 6-10 are pending. Favorable reconsideration is respectfully requested.

The present invention relates to a method for cleaning a resist residue on a microstructure comprising fluidizing a cleaning agent composition containing carbon dioxide and 0.0001 to 0.05% by mass of hydrogen fluoride under a pressure of 5 Mpa or more, and bringing the cleaning agent composition into contact with a microstructure. See Claims 1 and 7.

The rejection of the claims under 35 U.S.C. §102(b) over Koch is respectfully traversed. Koch fails to describe the claimed method.

Koch discloses a method of removing polishing residue from a substrate. See the Abstract.

Koch differs from the claimed method in at least two ways. First, the claimed method is directed to cleaning a resist residue on a microstructure. Koch does not describe cleaning a resist residue on a microstructure, but rather discloses a method of removing polishing residue from a substrate. In addition, the highest amount of hydrogen fluoride specified in the claimed method, i.e., 0.05% by mass, is much lower than the lowest amount specified in Koch, i.e., 0.096%.

This value is calculated as follows. Koch discloses 0.1 to 15 v/v% as the concentration of hydrogen fluoride. According to the Applicants, that range corresponds to 0.096 to 55.6wt%.

In view of the foregoing, Koch fails to disclose the claimed method. Moreover, there is no suggestion in that reference for the claimed method. Accordingly, withdrawal of this ground of rejection is respectfully requested.

The rejection of Claims 1 and 5 under 35 U.S.C. §112, second paragraph, is believed to be obviated by the amendment submitted above. Claim 5 has been canceled. The specification defines high pressure as "more than 5 Mpa." Therefore, that recitation in the claims makes explicit what was previously implicit. As such, that amendment is non-narrowing to the scope of the claims.

In view of the foregoing, the claims are definite within the meaning of 35 U.S.C. §112, second paragraph. Withdrawal of this ground of rejection is respectfully requested.

Applicants submit that the present application is in condition for allowance. Early notice to this effect is earnestly solicited.

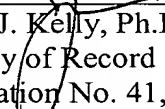
Respectfully submitted,

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